

AMENDMENTS TO THE CLAIMS

This listing of claims supersedes all prior versions and listings of claims in this application:

LISTING OF CLAIMS:

1. (Currently Amended) A flexible electronic device comprising: a flexible film; a substrate ~~formed~~ disposed on the flexible film, the substrate being different from the material of said flexible film and thickness of said substrate is larger than 0 μm and not larger than 200 μm ; and a thin film device ~~formed~~ disposed directly on the substrate.
2. (Currently Amended) The flexible electronic device according to claim 1, wherein said flexible electronic device ~~is formed by laminating~~ comprises a laminate of at least two or more components.
3. (Original) The flexible electronic device according to claim 1, wherein said thin film device is a thin film transistor formed of a silicon thin film.
4. (Original) The flexible electronic device according to claim 1, wherein said substrate is an insulating substrate.

5. (Original) The flexible electronic device according to claim 4, wherein said insulating substrate is a glass substrate.

6. (Original) The flexible electronic device according to claim 1, wherein said flexible film is an insulating film.

7. (Original) The flexible electronic device according to claim 1, wherein said flexible film has a thermal conductivity higher than 0.01 W/cm·deg.

8. (Currently Amended): The flexible electronic device according to claim 1, wherein said flexible film is a laminated structure at least comprising a film having a thermal conductivity higher than 0.01 ~~W/cm·deg~~ W/cm·deg and an insulating film.

9-22. (Cancelled).

Please add the following new claims 23-29:

23. (New): A flexible electronic device, comprising:
a first glass substrate and a second glass substrate, wherein each of said first glass substrate and said second glass substrate has a thin film device disposed on one surface thereof,

wherein said one surface, having a thin film device disposed thereon, of said first glass substrate and said second glass substrate adhere to each other;

wherein a thicknesses of said first glass substrate is larger than 0 μm and not larger than 200 μm and a thickness of said second glass substrate is larger than 0 μm and not larger than 200 μm ; and

a first flexible film is adhered onto a first glass substrate side opposite of said one surface, having a thin film device disposed thereon, and a second flexible film is adhered onto a second glass substrate side opposite of said one surface, having a thin film device disposed thereon.

24. (New): The flexible electronic device according to claim 23, wherein said flexible electronic device is a liquid crystal display device.

25. (New): The flexible electronic device according to claim 24, wherein at least one of said first and second flexible films has at least one of a polarizing function and a phase difference function.

26. (New): The flexible electronic device according to claim 24, wherein at least one of said first and second flexible films is reflective.

27. (New): A flexible electronic device comprising: a flexible film; a substrate disposed on the flexible film, the substrate being different from the material of said flexible film and thickness of said substrate is larger than 0 μm and not larger than 200 μm ; and a thin film device disposed on the substrate,

wherein said thin film device is a thin film transistor formed of a silicon thin film.

28. (New): A flexible electronic device comprising: a flexible film; a substrate disposed on the flexible film, the substrate being different from the material of said flexible film and thickness of said substrate is larger than 0 μm and not larger than 200 μm ; and a thin film device disposed on the substrate,

wherein said flexible film has a thermal conductivity higher than 0.01 W/cm \cdot deg.

29. (New): A flexible electronic device comprising: a flexible film; a substrate disposed on the flexible film, the substrate being different from the material of said flexible film and thickness of said substrate is larger than 0 μm and not larger than 200 μm ; and a thin film device disposed on the substrate,

wherein said flexible film is a laminated structure at least comprising a film having a thermal conductivity higher than 0.01 W/cm \cdot deg and an insulating film.